Jae Hyeong Park

List of Publications by Year
in descending order

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210 papers	2,229 citations	257450 24 h-index	302126 39 g-index
210 all docs	210 docs citations	210 times ranked	1262 citing authors

#	Article	IF	Citations
1	Effects of Cu/Al intermetallic compound (IMC) on copper wire and aluminum pad bondability. IEEE Transactions on Components and Packaging Technologies, 2003, 26, 367-374.	1.3	178
2	Design and understanding of anisotropic conductive films (ACF's) for LCD packaging. IEEE Transactions on Components and Packaging Technologies, 1998, 21, 226-234.	0.7	146
3	Comparison of theoretical predictions and experimental values of the dielectric constant of epoxy/BaTiO3 composite embedded capacitor films. Journal of Materials Science: Materials in Electronics, 2005, 16, 77-84.	2.2	86
4	Thermally resistant UV-curable epoxyâ€“siloxane hybrid materials for light emitting diode (LED) encapsulation. Journal of Materials Chemistry, 2012, 22, 8874.	6.7	71
5	A study on interfacial reactions between electroless Ni-P under bump metallization and 95.5Sn-4.0Ag-0.5Cu alloy. Journal of Electronic Materials, 2003, 32, 548-557.	2.2	70
6	Ultrathin Nanofibrous Membranes Containing Insulating Microbeads for Highly Sensitive Flexible Pressure Sensors. ACS Applied Materials & Interfaces, 2020, 12, 13348-13359.	8.0	69
7	High performance encapsulant for light-emitting diodes (LEDs) by a solâ€“gel derived hydrogen siloxane hybrid. Journal of Materials Chemistry, 2012, 22, 7954.	6.7	67
8	The effect of the oxidation of Cu-base leadframe on the interface adhesion between Cu metal and epoxy molding compound. IEEE Transactions on Advanced Packaging, 1997, 20, 167-175.	0.6	54
9	Grain Morphology of Intermetallic Compounds at Solder Joints. Journal of Materials Research, 2002, 17, 597-599.	2.6	51
10	Studies of electroless nickel under bump metallurgyâ€”Solder interfacial reactions and their effects on flip chip solder joint reliability. Journal of Electronic Materials, 2002, 31, 520-528.	2.2	42
11	Effect of nonconducting filler additions on ACA properties and the reliability of ACA flip-chip on organic substrates. IEEE Transactions on Components and Packaging Technologies, 2001, 24, 24-32.	1.3	40
12	Effects of Cu contents in Pb-free solder alloys on interfacial reactions and bump reliability of Pb-free solder bumps on electroless Ni-P under-bump metallurgy. Journal of Electronic Materials, 2005, 34, 80-90.	2.2	38
13	A study on the resistivity and mechanical properties of modified nano-Ag coated Cu particles in electrically conductive adhesives. Journal of Materials Science: Materials in Electronics, 2019, 30, 9171-9183.	2.2	38
14	Flip chip interconnection with anisotropic conductive adhesives for RF and high-frequency applications. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 789-796.	1.3	33
15	A Study on the Failure Mechanism and Enhanced Reliability of Sn58Bi Solder Anisotropic Conductive Film Joints in a Pressure Cooker Test Due to Polymer Viscoelastic Properties and Hydroswelling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 216-223.	2.5	33
16	Highly reliable non-conductive adhesives for flip chip CSP applications. IEEE Transactions on Electronics Packaging Manufacturing, 2003, 26, 150-155.	1.4	31
17	Bending Properties of Anisotropic Conductive Films Assembled Chip-in-Flex Packages for Wearable Electronics Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 208-215.	2.5	31
18	Screen printable epoxy/BaTiO₃ embedded capacitor pastes with high dielectric constant for organic substrate applications. Journal of Applied Polymer Science, 2008, 110, 798-807.	2.6	30

#	Article	IF	Citations
19	Reduced thermal strain in flip chip assembly on organic substrate using low CTE anisotropic conductive film. IEEE Transactions on Electronics Packaging Manufacturing, 2000, 23, 171-176.	1.4	29
20	Highly reliable flip-chip-on-flex package using multilayered anisotropic conductive film. Journal of Electronic Materials, 2004, 33, 76-82.	2.2	29
21	Studies on the Thermal Cycling Reliability of BGA System-in-Package (SiP) With an Embedded Die. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 625-633.	2.5	29
22	Effects of Pd addition on Au stud bumps/Al pads interfacial reactions and bond reliability. Journal of Electronic Materials, 2004, 33, 1210-1218.	2.2	27
23	Effect of electromigration on mechanical shear behavior of flip chip solder joints. Journal of Materials Research, 2006, 21, 698-702.	2.6	27
24	A Study on the Solder Ball Size and Content Effects of Solder ACFs for Flex-on-Board Assembly Applications Using Ultrasonic Bonding. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 9-14.	2.5	24
25	A Study on the Optimization of Anisotropic Conductive Films for Sn-3Ag-0.5Cu-Based Flex-on-Board Application at a 250 Â°C Bonding Temperature. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 383-391.	2.5	24
26	Effect of Nanofiber Orientation on Nanofiber Solder Anisotropic Conductive Films Joint Properties and Bending Reliability of Flex-on-Flex Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1317-1329.	2.5	23
27	Joint Morphologies and Failure Mechanisms of Anisotropic Conductive Films (ACFs) During a Power Handling Capability Test for Flex-On-Board Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1820-1826.	2.5	23
28	A Study on the Bonding Conditions and Nonconductive Filler Contents on Cationic Epoxy-Based Snâ€“58Bi Solder ACFs Joints for Reliable Flex-on-Board Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 2087-2094.	2.5	23
29	Effects of fine size lead-free solder ball on the interfacial reactions and joint reliability. , 2010, , .		22
30	Study on Fine Pitch Flex-on-Flex Assembly Using Nanofiber/Solder Anisotropic Conductive Film and Ultrasonic Bonding Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 2108-2114.	2.5	21
31	The Effect of Anisotropic Conductive Films Adhesion on the Bending Reliability of Chip-in-Flex Packages for Wearable Electronics Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1583-1591.	2.5	21
32	Epoxy/BaTiO/sub 3/ composite films and pastes for high dielectric constant and low-tolerance embedded capacitors fabrication in organic substrates. IEEE Transactions on Electronics Packaging Manufacturing, 2005, 28, 297-303.	1.4	19
33	Ultrasonic Bonding Using Anisotropic Conductive Films (ACFs) for Flip Chip Interconnection. IEEE Transactions on Electronics Packaging Manufacturing, 2009, 32, 241-247.	1.4	19
34	Nanofiber anisotropic conductive adhesives (ACAs) for ultra fine pitch chip-on-film (COF) packaging. , 2011, , .		19
35	Effects of Anisotropic Conductive Film Viscosity on ACF Fillet Formation and Chip-On-Board Packages. IEEE Transactions on Electronics Packaging Manufacturing, 2009, 32, 74-80.	1.4	17
36	High reliable non-conductive adhesives for flip chip CSP applications. , 0, , .		16

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37	The effect of T/sub g/ on thermo-mechanical deformation and reliability of adhesive flip chip assemblies during temperature cycling. , 0, , .		16
38	Comparison of interfacial reactions and reliabilifies of Sn3.5Ag, Sn4.0Ag0.5Cu, and Sn0.7Cu solder bumps on electroless Ni-P UBMs. , 2003, , .		15
39	A Study on the Thermal Reliability of Cu/SnAg Double-Bump Flip-Chip Assemblies on Organic Substrates. Journal of Electronic Materials, 2008, 37, 1832-1842.	2.2	15
40	A Study of Hygrothermal Behavior of ACF Flip Chip Packages With MoirÃ© Interferometry. IEEE Transactions on Components and Packaging Technologies, 2010, 33, 215-221.	1.3	15
41	Effects of the Mechanical Properties of Polymer Resin and the Conductive Ball Types of Anisotropic Conductive Films on the Bending Properties of Chip-in-Flex Package. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 200-207.	2.5	15
42	Contraction stress build-up of anisotropic conductive films (ACFs) for flip-chip interconnection: Effect of thermal and mechanical properties of ACFs. Journal of Applied Polymer Science, 2004, 93, 2634-2641.	2.6	14
43	Wafer-Level Flip Chip Packages Using Preapplied Anisotropic Conductive Films (ACFs). IEEE Transactions on Electronics Packaging Manufacturing, 2007, 30, 221-227.	1.4	14
44	Cu/SnAg Double Bump Flip Chip Assembly as an Alternative of Solder Flip Chip on Organic Substrates for Fine Pitch Applications. , 2007, , .		13
45	Theoretical Prediction and Experimental Measurement of the Degree of Cure of Anisotropic Conductive Films (ACFs) for Chip-On-Flex (COF) Applications. Journal of Electronic Materials, 2008, 37, 1580-1590.	2.2	13
46	A novel double layer NCF for highly reliable micro-bump interconnection. , 2014, , .		13
47	Stresses in electroless Ni-P films for electronic packaging applications. IEEE Transactions on Components and Packaging Technologies, 2002, 25, 169-173.	1.3	12
48	Frequency and Temperature Dependence of Dielectric Constant of Epoxy/BaTiO3Composite Embedded Capacitor Films (ECFs) for Organic Substrate. , 2005, , .		12
49	Epoxy/BaTiO3 (SrTiO3) Composite Films and Pastes For High Dielectric Constant and Low Tolerance Embedded Capacitors in Organic Substrates. , 2006, , .		12
50	Effects of Conductive Particles on the Electrical Stability and Reliability of Anisotropic Conductive Film Chip-on-Board Interconnections. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 359-366.	2.5	12
51	Interfacial reactions and bump reliability of various Pb-free solder bumps on electroless Ni-P UBMs. , 0, , .		11
52	Effects of the Functional Groups of Nonconductive Films (NCFs) on Material Properties and Reliability of NCF Flip-Chip-On-Organic Boards. IEEE Transactions on Components and Packaging Technologies, 2007, 30, 464-471.	1.3	11
53	Effect of Ag Addition on the Ripening Growth of ${m Cu}_{6}{m Sn}_{5}$ Grains at the Interface of Sn-xAg-0.5Cu/Cu During a Reflow. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1939-1946.	2.5	11
54	Flux function added solder anisotropic conductive films (ACFs) for high power and fine pitch assemblies. , 2013, , .		11

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55	Nanofiber Anisotropic Conductive Films (ACF) for Ultra-Fine-Pitch Chip-on-Glass (COG) Interconnections. Journal of Electronic Materials, 2015, 44, 4628-4636.	2.2	11
56	Under bump metallurgy study for Pb-free bumping. Journal of Electronic Materials, 2002, 31, 478-487.	2.2	10
57	A study on the temperature dependence of epoxy/BaTiO3 composite embedded capacitor films. Journal of Electronic Materials, 2005, 34, 1264-1269.	2.2	10
58	UbBM (under bump metallization) study for Pb-free electroplating bumping : interface reaction and electromigration. , 2002, , .		9
59	Adhesion and Reliability of Anisotropic Conductive Films (ACFs) Joints on Organic Solderability Preservatives (OSPs) Metal Surface Finish. Journal of Electronic Materials, 2008, 37, 1003-1011.	2.2	9
60	Thermal cycling reliability of Cu/SnAg double-bump flip chip assemblies for 100â€‚Î¼m pitch applications. Journal of Applied Physics, 2009, 105, .	2.5	9
61	Effects of the Degree of Cure on the Electrical and Mechanical Behavior of Anisotropic Conductive Films. Journal of Electronic Materials, 2010, 39, 410-418.	2.2	9
62	Studies on the Polymer Adhesive Wafer Bonding Method Using Photo-Patternable Materials for MEMS Motion Sensors Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1118-1127.	2.5	9
63	A Study on the Double Layer Non Conductive Films (NCFs) for Fine-Pitch Cu-Pillar/Sn-Ag Micro-Bump Interconnection. , 2016, , .		9
64	A Study on the Nanofiber-Sheet Anisotropic Conductive Films (NS-ACFs) for Ultra-Fine-Pitch Interconnection Applications. Journal of Electronic Materials, 2017, 46, 167-174.	2.2	9
65	Analytical approach to evaluate shear stress in flip chip interconnection using NCA/ACF. , 0, , .		8
66	Wafer level packages (WLPs) using anisotropic conductive adhesives (ACAs) solution for flip-chip interconnections. , 2008, , .		8
67	Low temperature fine pitch Flex-on-Flex (FOF) assembly using nanofiber Sn58Bi solder anisotropic conductive films (ACFs) and ultrasonic bonding method. , 2013, , .		8
68	Effects of ACF Bonding Parameters on ACF Joint Characteristics for High-Speed Bonding Using Ultrasonic Bonding Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 177-182.	2.5	8
69	Acoustic Matching Layer Films Using B-Stage Thermosetting Polymer Resins for Ultrasound Transducer Applications. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2020, 67, 2148-2154.	3.0	8
70	Effect of non-conducting filler additions on anisotropic conductive adhesives (ACAs) properties and the reliability of ACAs flip chip on organic substrates. , 0, , .		7
71	Electromigration of Pb-Free Solder Flip Chip Using Electroless Ni-P/Au UBM. , 2007, , .		7
72	Study of the Formation of Bubbles in Rigid Substrate-Flexible Substrate Bonding Using Anisotropic Conductive Films and the Bubble Effects on Anisotropic Conductive Film Joint Reliability. Journal of Electronic Materials, 2007, 36, 56-64.	2.2	7

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73	Effect of Pd addition on ultra-fine pitch Au wire/Al pad interface. , 2010, , .		7
74	High-speed flex-on-board assembly method using anisotropic conductive films (ACFs) combined with room temperature ultrasonic (US) bonding for high-density module interconnection in mobile phones. , 2011, , .		7
75	3D-TSV vertical interconnection method using Cu/SnAg double bumps and B-stage non-conductive adhesives (NCAs). , 2012, , .		7
76	Analysis of 3D TSV Vertical Interconnection Using Pre-applied Nonconductive Films. Journal of Electronic Materials, 2014, 43, 4214-4223.	2.2	7
77	Effect of Flux Activators on the Solder Wettability of Solder Anisotropic Conductive Films. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 3-8.	2.5	7
78	Wafer level packages (WLPs) using B-stage non-conductive films (NCFs) for highly reliable 3D-TSV micro-bump interconnection. , 2015, , .		7
79	Effects of Polymer Ball Size and Polyvinylidene Fluoride Nanofiber on the Ball Capture Rate for 100-<inline-formula> <tex-math notation="LaTeX">$\mu ext{m}$ </tex-math> </inline-formula>-Pitch Flex-on-Flex Assembly Using Anisotropic Conductive Films and Ultrasonic Bonding Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1127-1134.	2.5	7
80	Piezoelectric Ceramics and Flexible Printed Circuitsâ€™ Interconnection Using Sn58Bi Solder Anisotropic Conductive Films for Flexible Ultrasound Transducer Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1897-1903.	2.5	7
81	Relationships between suspension formulations and the properties of BaTiO/sub 3//epoxy composite films for integral capacitors. , 0, , .		6
82	Effect of compressive stresses in anisotropic conductive films (ACFs) on contact resistance of flip chip joint. , 0, , .		6
83	Embedded chip-in-flex (CIF) packages using wafer level package (WLP) with pre-applied anisotropic conductive films (ACFs). , 2009, , .		6
84	Effect of fine solder ball diameters on intermetallic growth of Sn-Ag-Cu solder at Cu and Ni pad finish interfaces during thermal aging. , 2011, , .		6
85	Effects of PCB Pad Metal Finishes on the Cu-Pillar/Sn-Ag Micro Bump Joint Reliability of Chip-on-Board (COB) Assembly. Journal of Electronic Materials, 2016, 45, 3208-3219.	2.2	6
86	Effects of particle size on dielectric constant and leakage current of epoxy/barium titanate (BaTiO/sub) Tj ETQq0 0 0 rgBT /Overlock 10 T		5
87	Low tolerance epoxy/BaTiO/sub 3/ composite embedded capacitor films (ECFs). , 0, , .		5
88	Wafer Level Packages (WLPs) using Pre-Applied Anisotropic Conductive Films (ACFs). , 2007, , .		5
89	Effects of Thermal Cycling on Material Properties of Nonconductive Pastes (NCPs) and the Relationship Between Material Properties and Warpage Behavior During Thermal Cycling. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 559-565.	1.3	5
90	Effects of Heating Rate on Material Properties of Anisotropic Conductive Film (ACF) and Thermal Cycling Reliability of ACF Flip Chip Assembly. IEEE Transactions on Components and Packaging Technologies, 2009, 32, 339-346.	1.3	5

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91	Wafer-Level Packages Using Anisotropic Conductive Adhesives (ACAs) Solution for Flip-Chip Interconnections. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 792-797.	2.5	5
92	Investigation of various photo-patternable adhesive materials and their processing conditions for MEMS sensor wafer bonding. , 2011, , .		5
93	Ultra-thin chip-in-flex (CIF) technology using anisotropic conductive films (ACFs) for wearable electronics applications. , 2015, , .		5
94	Fabrication and Characterization of Epoxy Molding Films (EMFs) for Wafer-Level and Panel-Level Fan Out Packages. , 2018, , .		5
95	A Study on the Curing Properties and Viscosities of Non-Conductive Films (NCFs) for Sn-Ag Solder Bump Flip Chip Assembly. , 2018, , .		5
96	Low-Temperature Bonding of PZT (PbZrTiO3) and Flexible Printed Circuits Using Sn52In Solder Anisotropic Conductive Films for Flexible Ultrasonic Transducers. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2152-2159.	2.5	5
97	Novel epoxy/BaTiO/sub 3/ composite embedded capacitor films embedded in organic substrates. , 0, , .		4
98	The effects of the degree of cure of anisotropic conductive films (ACFs) on the contraction stress build-up of ACFs and ACF joints stability for chip-on-flex (COF) applications. , 2009, , .		4
99	Nonconductive Films (NCFs) With Multifunctional Epoxies and Silica Fillers for Reliable NCFs Flip Chip on Organic Boards (FCOBs). IEEE Transactions on Electronics Packaging Manufacturing, 2009, 32, 65-73.	1.4	4
100	Reduced Temperature Coefficient of Capacitance (TCC) of Embedded Capacitor Films (ECFs) for Organic Substrates using SrTiO3 and Multifunctional Epoxy. Journal of Electronic Materials, 2010, 39, 1358-1363.	2.2	4
101	Advancing Electronic Packaging Using Microsolder Balls: Making 25-nm Pitch Interconnection Possible. IEEE Nanotechnology Magazine, 2013, 7, 24-30.	1.3	4
102	Effects of Nanofiber on the Electrical Properties of Anisotropic Conductive Adhesives (ACAs). Journal of Nanoscience and Nanotechnology, 2013, 13, 351-355.	0.9	4
103	Effects of Curing Agent and Curing Temperature on Material Properties of Epoxy/BaTiO₃ Composite Embedded Capacitor Films. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 451-459.	2.5	4
104	Effects of Cooling Processes and Silica Filler Contents of Solder ACFs (Anisotropic Conductive Films) on the Joints Reliability. , 2016, , .		4
105	A Study on the Cu-Rod Anisotropic Conductive Films (ACFs) for Flex-on-Fabric (FOF) Interconnections Using an Ultrasonic Bonding Method. , 2016, , .		4
106	A Study on the Fabrication of Electrical Circuits on Fabrics Using Cu Pattern Laminated B-Stage Adhesive Films for Electronic Textile Applications. , 2017, , .		4
107	New anisotropic conductive adhesives for low cost and reliable flip chip on organic substrates applications. , 0, , .		3
108	Evaluation of thermal shear strains in flip-chip package by electronic speckle pattern interferometry (ESPI). , 0, , .		3

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109	In-situ moire measurement of adhesive flip-chip bonded assembly under thermal cycling condition. , 0, , .		3
110	The experimental and theoretical approaches of contraction stress build-up of anisotropic conductive adhesives for flip chip interconnection. , 0, , .		3
111	Wafer-Level Package using Pre-Applied Anisotropic Conductive Films (ACFs) for Flip-Chip Interconnections. , 0, , .		3
112	Fabrication and characterization of embedded capacitors in printed circuit boards using B-stage epoxy/BaTiO<inf>3</inf> composite embedded capacitor films (ECFs). , 2008, , .		3
113	Effects of epoxy and rubber addition on die attach films (DAFs) materials properties. , 2009, , .		3
114	Characterization of epoxy/BaTiO<inf>3</inf> composite embedded capacitors for high frequency behaviors. , 2009, , .		3
115	High speed touch screen panels (TSPs) assembly using anisotropic conductive adhesives (ACAs) vertical ultrasonic bonding method. , 2010, , .		3
116	Effect of Ag on ripening growth of Cu<inf>6</inf>Sn<inf>5</inf> grains formed between molten Sn-xAg-0.5Cu solders and Cu. , 2010, , .		3
117	A study on the 3D-TSV interconnection using wafer-level non-conductive adhesives (NCAs). , 2011, , .		3
118	Vertically aligned nickel nanowire/epoxy composite for electrical and thermal conducting material. , 2012, , .		3
119	Low temperature curable anisotropic conductive films (ACFs) with photo-active curing agent (PA-ACFs). , 2012, , .		3
120	Ultrasonic Bonding of Anisotropic Conductive Films Containing Ultrafine Solder Balls for High-Power and High-Reliability Flex-On-Board Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 884-889.	2.5	3
121	Ultrasonic-assisted thermo-compression bonding method for high-performance solder anisotropic conductive film (ACF) joints. , 2012, , .		3
122	Micro-solder/adhesive hybrid joints for high-density, high-power, high-reliability, and reworkable module interconnection in mobile phones. , 2012, , .		3
123	A study on the fine pitch chip interconnection using Cu/SnAg bumps and B-stage non-conductive films (NCFs) for 3D-TSV vertical interconnection. , 2014, , .		3
124	A novel fine pitch TSV interconnection method using NCF with Zn nano-particles. , 2014, , .		3
125	Low-Temperature Curable Photo-Active Anisotropic Conductive Films (PA-ACFs). Journal of Electronic Materials, 2014, 43, 3236-3242.	2.2	3
126	Effects of ACFs Adhesion on the Bending Reliability of Chip-in-Flex Packages for Wearable Electronics Applications. , 2016, , .		3

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127	Thermo-Compression Bonding Using Non-conductive Films (NCFs) for 3-D TSV Micro-Bump Interconnection. , 2016, , .		3
128	Effects of ACFs Modulus and Adhesion Strength on the Bending Reliability of CIF (Chip-in-Flex) Packages at Humid Environment. , 2018, , .		3
129	Effects of the Curing Properties and Viscosities of Non-Conductive Films (NCFs) on the Sn-Ag Solder Bump Joint Morphology and Reliability. , 2019, , .		3
130	Low Temperature Oxidation of Cu-Base Leadframe and Cu/Emc Interface Adhesion. Materials Research Society Symposia Proceedings, 1996, 445, 275.	0.1	2
131	Title is missing!. Journal of Materials Science Letters, 1999, 18, 1645-1648.	0.5	2
132	Pb-free bumping technology and UBM (under bump metallurgy). , 0, , .		2
133	Investigation of UBM systems for electroplated Sn/37Pb and Sn/3.5Ag solder. , 2001, , .		2
134	Investigation of low cost flip chip under bump metailization (UBM) systems on Cu pads. , 0, , .		2
135	Effects of the Functional Groups of Non-Conductive Films (NCFs) on Materials Properties and Reliability of NCF Flip-Chip-On-Organic Boards. , 0, , .		2
136	Assembly Yield Enhancement of Electroless Ni-P UBM/Pb-free Solder Joints. , 0, , .		2
137	Bubbles Formation in Rigid-Flexible Substrates Bonding using Anisotropic Conductive Films (ACFs) and Their Effects on ACFs Joints Reliability. , 0, , .		2
138	Effect of Sb addition in Sn-Ag-Cu solder balls on the drop test reliability of BGA packages with electroless nickel immersion gold (ENIG) surface finish. , 2007, , .		2
139	Non-Conductive Films (NCFs) with Multi-Functional Epoxies and Silica Fillers for Reliable NCFs Flip Chip On Organic Boards (FCOB). , 2007, , .		2
140	Wafer Level ACA Packages and their Applications to Advanced Electronic Packaging. , 2008, , .		2
141	Effects of fine size lead-free solder ball on the interfacial reactions and joint reliability. , 2009, , .		2
142	High productivity and damage-free ultrasonic anisotropic conductive film (ACF) bonding for touch screen panel (TSP) assemblies. , 2012, , .		2
143	A study on the intermetallic growth of fine-pitch Cu pillar/SnAg solder bump for 3D-TSV interconnection. , 2012, , .		2
144	3D-TSV vertical interconnection method using Cu/SnAg double bumps. , 2012, , .		2

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145	Investigation of interfacial phenomena of alloyed Au wire bonding. , 2013, , .		2
146	Effects of nanofiber materials of nanofiber anisotropic conductive adhesives (nanofiber ACAs) for ultra-fine pitch electronic assemblies. , 2013, , .		2
147	Ultrasonic-Assisted Thermocompression Bonding Method of Solder Anisotropic Conductive Film Joints for Reliable Camera Module Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 2156-2163.	2.5	2
148	Effects of Anisotropic Conductive Films (ACFs) Gap Heights on the Bending Reliability of Chip-In-Flex (CIF) Packages for Wearable Electronics Applications. , 2017, , .		2
149	The Effect of Polymer Rebound on SnBi58 Solder ACFs Joints Cracks during a Thermo-Compression Bonding. , 2017, , .		2
150	Low Temperature Transient Liquid Phase (TLP) Bonding using Eutectic Sn-In Solder Anisotropic Condctive Films (ACFs) for Flexible Ultrasound Transducer. , 2019, , .		2
151	A Study on the Conductive Particle Movements in Polyvinylidene Fluoride Anchoring Polymer Layer Anisotropic Conductive Films for 20-<inline-formula> <tex-math notation="LaTeX">mu </tex-math> </inline-formula>m Fine-Pitch Interconnection. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 209-215.	2.5	2
152	IMCs Microstructure Evolution Dependence of Mechanical Properties for Ni/Sn/Ni Micro Solder-Joints. Materials, 2020, 13, 252.	2.9	2
153	Design and understanding of anisotropic conductive films (ACFs) for LCD packaging. , 0, , .		1
154	Study on the epoxy/BaTiO/sub 3/ embedded capacitor films newly developed for PWB applications. , 0, , .		1
155	Conduction mechanism of anisotropic conductive adhesives (ACAs): conductor ball deformation and build-up of contraction stresses. , 0, , .		1
156	Multi-functional epoxy/SrTiO/sub 3/ ceramic powder embedded capacitor films(ECFs) for organic substrates. , 2006, , .		1
157	Study on Bubble Formation in Rigid-Flexible Substrates Bonding using Anisotropic Conductive Films (ACFs) and Their Effects on the ACF Joint Reliability. , 0, , .		1
158	Thermal cycling reliability of Cu/SnAg double-bump flip-chip assemblies for 100um pitch applications. , 2007, , .		1
159	Adhesion and Reliability of Anisotropic Conductive Films (ACFs) Joints on Organic Solderability Preservatives (OSPs) Metal Surface Finish. , 2007, , .		1
160	Effect of electoless Ni/Au UBM thickness on mechanical and electromigration relibility of Pb-free solder joints. , 2007, , .		1
161	A Novel Anisotropic Conductive Film (ACF) Bonding Method Using Vertical Ultrasonic Vibration. , 2008, , .		1
162	Studies on the Thermal Cycling Reliability of Fine Pitch Cu/SnAg Double-Bump Flip Chip Assemblies on Organic Substrates: Experimental Results and Numerical Analysis. , 2008, , .		1

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163	Bumpless Ball Grid Array (BBGA) package using a solder resist cavity. , 2009, , .		1
164	Recent advances in anisotropic conductive adhesives (ACAs) materials and processing technology. , 2010, , .		1
165	Effects of bonding parameters and ACF material properties on the ACF joint morphology in ultrasonic bonding. , 2011, , .		1
166	High temperature reliability of Pd-alloyed Au wire/Al bonding interface. , 2012, , .		1
167	Effect of aligned nanofiber in nanofiber solder anisotropic conductive films (ACFs) on the solder ball movement for flex-on-flex (FOF) assembly. , 2014, , .		1
168	Effects of pad surface finish on interfacial reliabilities of Cu-pillar/Sn-Ag bumps of 2.5D TSV-enterposer on PCB applications. , 2014, , .		1
169	Warpage Behavior and Life Prediction of a Chip-on-Flex Package Under a Thermal Cycling Condition. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1144-1151.	2.5	1
170	Moisture Effects on NCF Adhesion and Solder Joint Reliability of Chip-on-Board Assembly Using Cu Pillar/Snâ€“Ag Microbump. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 371-378.	2.5	1
171	The Effect of the SnAg Solder Joint Morphology on the Thermal Cycle Reliability of 40 Âµm Fine-Pitch Cu-Pillar/SnAg Micro Bump Interconnection. , 2018, , .		1
172	Effects of the Adhesion Strength on the Bending Fatigue Behavior of Cu Pattern Laminated Fabrics Using B-Stage Non-Conductive Films (NCFs). , 2018, , .		1
173	A Study on the Anchoring Polymer Layer(APL) Solder Anisotropic Conductive Films (ACFs) for Ultra Fine Pitch Flex-on-Flex (FOF) Assembly Using an Ultrasonic Bonding Method. , 2018, , .		1
174	Effects of the Materials Properties of Epoxy Molding Films (EMFs) on Fan-Out Packages (FOPs) Characteristics. , 2019, , .		1
175	The Effect of the Thermal Mechanical Properties of Nonconductive Films on the Thermal Cycle Reliability of 40-<inline-formula> <tex-math notation="LaTeX">mu </tex-math> </inline-formula>m Fine Pitch Cu-Pillar/Ni/SnAg Microbump Flip-Chip Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 10-17.	2.5	1
176	Epoxy/TaTiO/sub 3/ composite films and pastes for high dielectric constant and low tolerance embedded capacitors fabrication in organic substrates. , 0, , .		0
177	Exothermic Reaction Induced Eutectic Pbâ€“Sn Solder Ball Melting in the Underfill Curing Process. IEEE Transactions on Components and Packaging Technologies, 2004, 27, 172-176.	1.3	0
178	Frequency Behavior of Embedded Epoxy/SrTiO3 Composite Capacitor Materials. , 0, , .		0
179	Epoxy/BaTiO/sub 3/(SrTiO/sub 3/) composite films for high dielectric constant and low tolerance embedded capacitors fabrication in organic substrates. , 0, , .		0
180	Studies on Double-Layered Metal Bumps for Fine Pitch Flip Chip Applications. , 0, , .		0

#	Article	IF	Citations
181	Novel Non-Conductive Films(NCFs) with Multi-Functional Epoxies and Silica Fillers for Reliable NCFs Flip-Chip-On-Organic Boards. , 2006, , .		0
182	Electromigration of Pb-free solder flip chip using electroless Ni-P/Au UBM. , 2006, , .		0
183	Effects of metal surface finish on the anisotropic conductive adhesives (ACAs) joints. , 2006, , .		0
184	Thermal stability at the anisotropic conductive films (ACFs)/ organic solderability preservatives (OSPs) Interface. , 2007, , .		0
185	Effects of anisotropic conductive film (ACF) viscosity on ACF fillet and moisture-related reliability for flip-chip-on-board (FCOB) packages. , 2007, , .		0
186	Effects of Heating Rate During ACFs Curing Process on Material Properties and Thermal Cycling Reliability of Flip Chip Assembly. , 2007, , .		0
187	Fabrication and characterization of Epoxy/BaTiO<inf>3</inf> composite capacitor films for high frequency behaviors. , 2007, , .		0
188	Theoretical prediction and experimental measurement of the degree-of-cure of anisotropic conductive film (ACF) for chip-on-flex (COF) applications. , 2007, , .		0
189	Room temperature ACF bonding process using ultrasonic vibration for chip-on-board and flex-on-board applications. , 2007, , .		0
190	Fabrication and characterization of epoxy/BaTiO<inf>3</inf> composite embedded capacitor for high frequency behaviors. , 2008, , .		0
191	The effects of the degree of cure of anisotropic conductive films (ACFs) on the contraction stress build-up of ACFs and ACF joints stability for ACF flip-chip interconnection. , 2008, , .		0
192	Patterning of wafer level applied non-conductive adhesives (NCAs) for camera image sensor (CIS) modules. , 2009, , .		0
193	Reliability enhancement of embedded capacitors in printed circuit boards using B-stage epoxy/BaTiO<inf>3</inf> composite embedded capacitor films (ECFs). , 2009, , .		0
194	20 µm-pitch complaint-bump-bonded chip-on-flex by pre-applied wafer level adhesives. , 2009, , .		0
195	Studies on various 2-metal chip-on-flex (COF) packaging methods. , 2010, , .		0
196	Photo-patternable non-conductive adhesives (NCAs) for electronic packaging applications. , 2010, , .		0
197	Ultra low temperature curable anisotropic conductive films (ACFs) with photo latent curing behavior (PLC-ACFs). , 2011, , .		0
198	Study on the thermal cycle and drop test reliability of system-in-packages with an Embedded die. , 2011, , .		0

#	Article	IF	Citations
199	Bio-inspired surface treatment on touch screen panels (TSPs) for adhesion enhancement. , 2012, , .		0
200	Effect of NCFs with Zn-nanoparticles on the interfacial reactions of 40 um pitch Cu pillar/Sn-Ag bump for TSV interconnection. , 2013, , .		0
201	Fine pitch flex-on-flex (FOF) assembly using nanofiber solder anisotropic conductive films (ACFs) and ultrasonic bonding method. , 2013, , .		0
202	The effects of self-fluxing additives in solder anisotropic conductive films (ACFs) on solder wettability and joint reliability of flex-on-board (FOB) assemblies. , 2014, , .		0
203	Effects of film viscosity on electric field-induced alignment of graphene flakes in B-stage graphene-epoxy composite films. , 2015, , .		0
204	Nanofiber ACFs (anisotropic conductive films) for ultra-fine pitch interconnection. , 2015, , .		0
205	A Study on the Novel Nylon Anchoring Polymer Layer(APL) Anisotropic Conductive Films(ACFs) for Ultra Fine Pitch Chip-on-Glass(COG) Applications. , 2017, , .		0
206	Effect of Material Properties of Double-Layer Non Conductive Films (D-NCFs) on the Reflow Reliability of Ultra Fine-Pitch Cu-Pillar/Sn-Ag Micro Bump Interconnection. , 2017, , .		0
207	A Study on the Fine Pitch Flex-on-Flex (FOF) Assembly Using Flux Added Nanofiber Solder Anisotropic Conductive Films (ACFs) and Thermo-Compression Bonding Method. , 2017, , .		0
208	A Study on the Preparation and Properties of Conductive Adhesive Filled with Multi-component Fillers for Green Packaging. , 2018, , .		0
209	Bending Properties of Fine Pitch Flexible CIF (Chip-in-Flex) Packages Using APL (Anchoring Polymer) Tj ETQq1 1 0.784314 rgBT /Overlo		0
210	A Study on the Anchoring Polymer Layer (APL) Anisotropic Conductive Films (ACFs) with Self-Exposed Conductive Particles Surface for Ultra-Fine Pitch Chip-on-Glass (COG) Applications. , 2019, , .		0